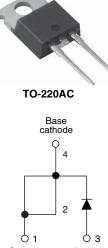


**Vishay Semiconductors** 

# HEXFRED<sup>®</sup> Ultrafast Soft Recovery Diode, 4 A



	2	<b>—</b>
Ó 1		Ó 3
Cathode		Anode

PRODUCT SUMMARY	
Package	TO-220AC
I <sub>F(AV)</sub>	4 A
V <sub>R</sub>	600 V
V <sub>F</sub> at I <sub>F</sub>	1.4 V
t <sub>rr</sub> typ.	17 ns
T <sub>J</sub> max.	150 °C
Diode variation	Single die

#### **FEATURES**

- Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>
- Designed and qualified according to JEDEC®-JESD47
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

### DESCRIPTION

VS-HFA04TB60... is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 4 A continuous current, the VS-HFA04TB60... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I<sub>RRM</sub>) and does not exhibit any tendency to "snap-off" during the t<sub>b</sub> portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA04TB60... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V <sub>R</sub>		600	V					
Maximum continuous forward current	١ <sub>F</sub>	T <sub>C</sub> = 100 °C	4						
Single pulse forward current	I <sub>FSM</sub>		25	А					
Maximum repetitive forward current	I <sub>FRM</sub>		16						
Maximum neuror discinction	P <sub>D</sub>	T <sub>C</sub> = 25 °C	25	W					
Maximum power dissipation		T <sub>C</sub> = 100 °C	10	- VV					
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C					

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<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS		
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA	600	-	-				
		I <sub>F</sub> = 4.0 A		-	1.5	1.8	V		
Maximum forward voltage	$V_{FM}$	I <sub>F</sub> = 8.0 A	See fig. 1	-	1.8	2.2			
		I <sub>F</sub> = 4.0 A, T <sub>J</sub> = 125 °C		-	1.4	1.7			
Maximum reverse	$V_{\rm R} = V_{\rm R}$ rated		See fig. 0	-	0.17	3.0			
leakage current	I <sub>RM</sub>	$T_J$ = 125 °C, $V_R$ = 0.8 x $V_R$ rated	See fig. 2	-	44	300	μA		
Junction capacitance	CT	V <sub>R</sub> = 200 V See fig. 3		-	4.0	8.0	pF		
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from p	ackage body	-	8.0	-	nH		

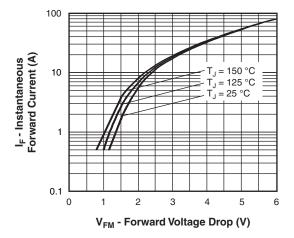
<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time See fig. 5, 6 and 16	t <sub>rr</sub>	$I_F = 1.0 \text{ A},  dI_F/dt = 200$	A/μs, V <sub>R</sub> = 30 V	-	17	-	ns		
	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	28	42			
	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	38	57			
Peak recovery current See fig. 7 and 8	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 4 A dI <sub>F</sub> /dt = 200 A/µs V <sub>R</sub> = 200 V	-	2.9	5.2	A		
	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	3.7	6.7			
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	40	60			
See fig. 9 and 10	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	70	105			
Peak rate of fall of recovery current during t <sub>b</sub> See fig. 11 and 12	dl <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	280	-	A // 10		
	dl <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	235	-	A/µs		

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C				
Thermal resistance, junction to case	R <sub>thJC</sub>		-	-	5.0					
Thermal resistance, junction to ambient	R <sub>thA</sub>	Typical socket mount	-	-	80	K/W				
Thermal resistance, case to heatsink	R <sub>thS</sub>	Mounting surface, flat, smooth and greased	-	0.5	-					
Weight			-	2.0	-	g				
weight			-	0.07	-	oz.				
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)				
Marking device		Case style TO-220AC	HFA04TB60							

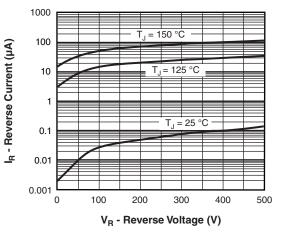
Revision: 22-Jun-15 Document Number: 94035 2 For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFI Downloaded From Oneyac.com

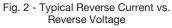


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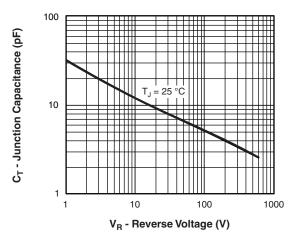


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

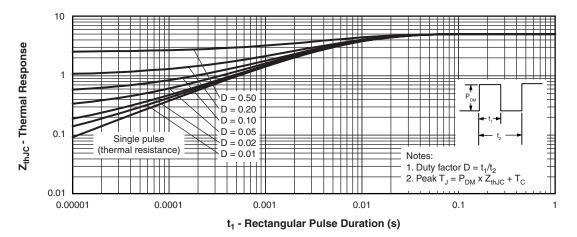
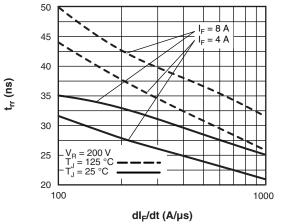


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics





www.vishay.com

Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

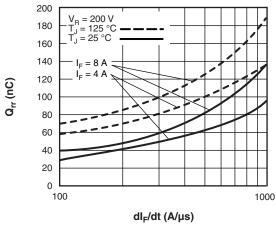


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt

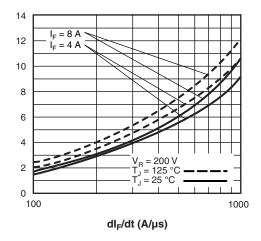


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt

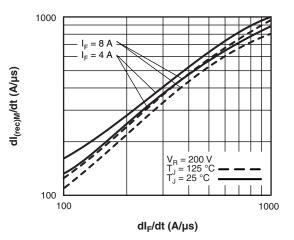


Fig. 8 - Typical dl<sub>(rec)M</sub>/dt vs. dl<sub>F</sub>/dt

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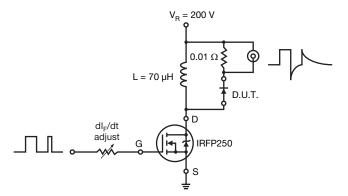


Fig. 9 - Reverse Recovery Parameter Test Circuit

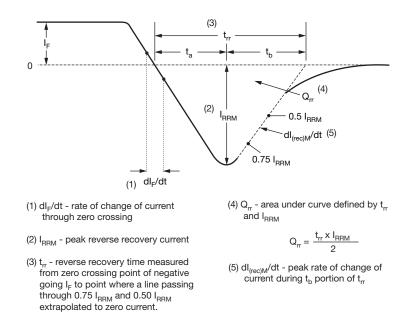


Fig. 10 - Reverse Recovery Waveform and Definitions



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#### **ORDERING INFORMATION TABLE**

Dev

ORDERING INFORMATION (Example)									
PREFERRED P/N QUANTITY PER T/R MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION									
VS-HFA04TB60PbF	50	1000	Antistatic plastic tube						
VS-HFA04TB60-N3	50	1000	Antistatic plastic tube						

LINKS TO RELATED DOCUMENTS								
Dimensions		www.vishay.com/doc?95221						
Part marking information	TO-220ACPbF	www.vishay.com/doc?95224						
Part marking information	TO-220AC-N3	www.vishay.com/doc?95068						



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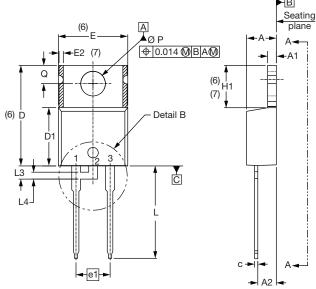
**TO-220AC** 

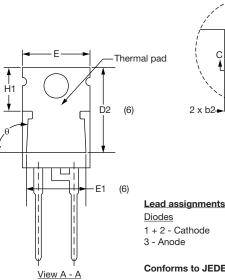
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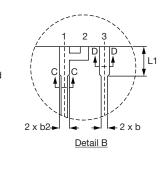
A-

plane

#### **DIMENSIONS** in millimeters and inches









**Diodes** 1 + 2 - Cathode 3 - Anode

Conforms to JEDEC outline TO-220AC

SYMBOL	MILLIM	IETERS	INC	HES	NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.25	4.65	0.167	0.183		E1	6.86	8.89	0.270	0.350	6
A1	1.14	1.40	0.045	0.055		E2	-	0.76	-	0.030	7
A2	2.56	2.92	0.101	0.115		е	2.41	2.67	0.095	0.105	
b	0.69	1.01	0.027	0.040		e1	4.88	5.28	0.192	0.208	
b1	0.38	0.97	0.015	0.038	4	H1	6.09	6.48	0.240	0.255	6, 7
b2	1.20	1.73	0.047	0.068		L	13.52	14.02	0.532	0.552	
b3	1.14	1.73	0.045	0.068	4	L1	3.32	3.82	0.131	0.150	2
С	0.36	0.61	0.014	0.024		L3	1.78	2.13	0.070	0.084	
c1	0.36	0.56	0.014	0.022	4	L4	0.76	1.27	0.030	0.050	2
D	14.85	15.25	0.585	0.600	3	ØР	3.54	3.73	0.139	0.147	
D1	8.38	9.02	0.330	0.355		Q	2.60	3.00	0.102	0.118	
D2	11.68	12.88	0.460	0.507	6	θ	90° t	o 93°	90° t	o 93°	
E	10.11	10.51	0.398	0.414	3, 6						

Notes

<sup>(1)</sup> Dimensioning and tolerancing as per ASME Y14.5M-1994

<sup>(2)</sup> Lead dimension and finish uncontrolled in L1

(3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

- (4) Dimension b1, b3 and c1 apply to base metal only
- <sup>(5)</sup> Controlling dimension: inches
- <sup>(6)</sup> Thermal pad contour optional within dimensions E, H1, D2 and E1
- <sup>(7)</sup> Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- <sup>(8)</sup> Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline

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